

RECEIVED  
CENTRAL FAX CENTER

Application No.: 10/755,042

JUL 20 2005

Docket No.: JCLA8533-D2

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:

Mou-Shiung Lin et al.

Serial No. : 10/755,042

Filed : January 9, 2004

For : INTEGRATED CHIP PACKAGE  
STRUCTURE USING SILICON  
SUBSTRATE AND METHOD OF  
MANUFACTURING THE SAME

Examiner : FENTY, JESSE A.

Art Unit : 2815

Docket No. : JCLA8533-D2

*the request  
entry 7/22/05*AMENDMENT AFTER FINAL

## MAIL STOP AF

Commissioner for Patents

P. O. Box 1450

Alexandria, VA 22313-1450

Dear Sir:

The Office Action mailed April 20, 2005 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.